

**IN THE CLAIMS**

Claims 1-12: Canceled.

13. Canceled.

14. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 22, wherein the dielectric layers comprise polyimide.

15. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 21, wherein the alignment plate comprises a metal or a metal alloy.

16. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 22, further comprising a release sheet positioned between the alignment plate and the nearest adjacent layer to be stacked.

17. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 15, wherein the metal or the metal alloy comprises copper.

18. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 21, further comprising at least one tooling pin coupled to the alignment plate.

19. (Currently Amended) The ~~interconnect of claim 13~~ plate of claim 18, wherein the tooling pins comprise a conical tip where each layer of the plurality of layers can be rested prior to forcing the tooling pins through the registration holes of each layer.

20. (Currently Amended) The ~~interconnect of claim 13~~ plate of one of claims 18 or 19, wherein the diameter of the registration holes is at most 5  $\mu\text{m}$  smaller than the diameter of the tooling pins.

21. (New) An alignment plate, comprising:

a plate having tooling pins with a diameter larger than the diameters of the registration holes and having approximately a TCE that differs from the average TCE of a plurality of dielectric layers by less than 2 ppm/ $^{\circ}\text{C}$ , wherein the plurality of dielectric layers are stacked onto the alignment plate.

22. (New) The alignment plate of claim 21, wherein the plurality of dielectric layers comprise at least two of the dielectric layers having different thermal coefficients of expansion and wherein the layers including a plurality of registration holes.